

Title (en)

COPPER ALLOY MATERIAL FOR ELECTRICAL/ELECTRONIC PART AND PROCESS FOR PRODUCING THE SAME

Title (de)

KUPFERLEGIERUNGSWERKSTOFF FÜR ELEKTRISCHES/ELEKTRONISCHES TEIL UND HERSTELLUNGSVERFAHREN DAFÜR

Title (fr)

ALLIAGE DE CUIVRE POUR PIÈCES ÉLECTRIQUES/ÉLECTRONIQUES, ET PROCÉDÉ DE FABRICATION ASSOCIÉ

Publication

**EP 2088215 A4 20120627 (EN)**

Application

**EP 07829424 A 20071009**

Priority

- JP 2007069686 W 20071009
- JP 2006276808 A 20061010
- JP 2007260386 A 20071003

Abstract (en)

[origin: US2009229716A1] A copper alloy material for electric/electronic parts, which is produced by the steps containing: finish rolling a copper alloy at a reduction ratio of 40% or less, subjecting the copper alloy finish-rolled to a heat treatment under the conditions at a temperature from 500° C. to 800° C. for a time period from 1 second to 100 seconds by means of a continuous annealing line, and strain relief annealing the copper alloy heat-treated under the conditions at a temperature from 400° C. to 600° C. for a time period from 30 seconds to 1000 seconds, wherein the copper alloy material for electric/electronic parts has rates of dimensional changes before and after the strain relief annealing in both directions parallel to and perpendicular to the rolling direction within the range from -0.02% to +0.02%.

IPC 8 full level

**C22C 9/06** (2006.01); **B21B 1/22** (2006.01); **B21B 3/00** (2006.01); **C22F 1/08** (2006.01); **H01B 1/02** (2006.01); **H01B 5/02** (2006.01); **H01B 13/00** (2006.01)

CPC (source: EP KR US)

**B21B 1/22** (2013.01 - KR); **C22C 9/06** (2013.01 - EP KR US); **C22F 1/00** (2013.01 - KR); **C22F 1/08** (2013.01 - EP US); **H01B 1/02** (2013.01 - KR); **B21B 3/00** (2013.01 - EP US)

Citation (search report)

- [X] JP 2004131829 A 20040430 - NIKKO METAL MFG CO LTD
- [XI] JP 2002317231 A 20021031 - NIPPON MINING CO
- [A] US 4656003 A 19870407 - MIYAFUJI MOTOHISA [JP], et al
- [A] JP 2004149873 A 20040527 - NIKKO METAL MFG CO LTD
- See references of WO 2008044680A1

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU LV MC MT NL PL PT RO SE SI SK TR

DOCDB simple family (publication)

**US 2009229716 A1 20090917**; EP 2088215 A1 20090812; EP 2088215 A4 20120627; JP 2008115465 A 20080522; JP 5170866 B2 20130327; KR 20090064473 A 20090618; TW 200829707 A 20080716; TW I412611 B 20131021; WO 2008044680 A1 20080417

DOCDB simple family (application)

**US 42112809 A 20090409**; EP 07829424 A 20071009; JP 2007069686 W 20071009; JP 2007260386 A 20071003; KR 20097008901 A 20090429; TW 96137423 A 20071005